The Top Assisting Partner in the AI Supply Chain

Empowering the success of clients across different ecosystems through high-level collaboration

C SUN 志聖工業

2026 Q2 Investor's meeting

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward-looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design in, time to market, market competition, industrial cyclicality, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations. global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
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G2C+ Alliance

Cross Holding Structure

CSun - Linkou
ASE
TSMC
GPM
GMM
TSMC
TSMC
C Sun
GPM
Chiayi
TSMC
TSMC
Tainan
Contrel
GPM
GMM
ASE
Kaohsiung
ASE
FLEXIBILITY
TELEMETRY
PRODUCTION HINTERLAND: BUILDING RESILIENCE
CONSOLIDATING 10,000-PING SPACE AT TSP & SHUGU: DELIVERING FLEXIBLE, GIANT-SCALE AUTOMATION & ASSEMBLY CAPACITY FOR THE ALLIANCE.
AUTOMATION
FLEXIBILITY
TELEMETRY
RAPID CO-development Network
ESTABLISHING LOCAL ZERO-DELAY SUPPORT MECHANISM: PROXIMITY SERVICE TO KEY ACCOUNTS, ENSURING STABLE HIGH-END EQUIPMENT OPERATION & JOINT DEVELOPMENT.
ZERO-TIME DEVELOPMENT SYNC
FERRARI
ROSSO CORSA

G2C+ Alliance: The Platform Advantage

Contrel (東捷)

- Laser Application (雷射應用)
- Sputtering & Dry Etching (真空濺鍍 & 乾蝕刻)

GMM (均華)

- Die Attach (黏晶)
- Chip Sorter (揀晶)

2,400+

聯盟總人數
(Total Alliance Workforce)

900+

研發人員
(R&D Personnel)

Sun (志聖)

- Thermal (熱)
- Bonder (壓合)
- Lamination (貼膜)
- Wet Process (濕製程)
- Peeling (撕膜)
- UV/Plasma (光/電漿)

GPM (均豪)

- AOI (檢測)
- Metrology (量測)
- Grinding (研磨)
- Polishing (拋光)

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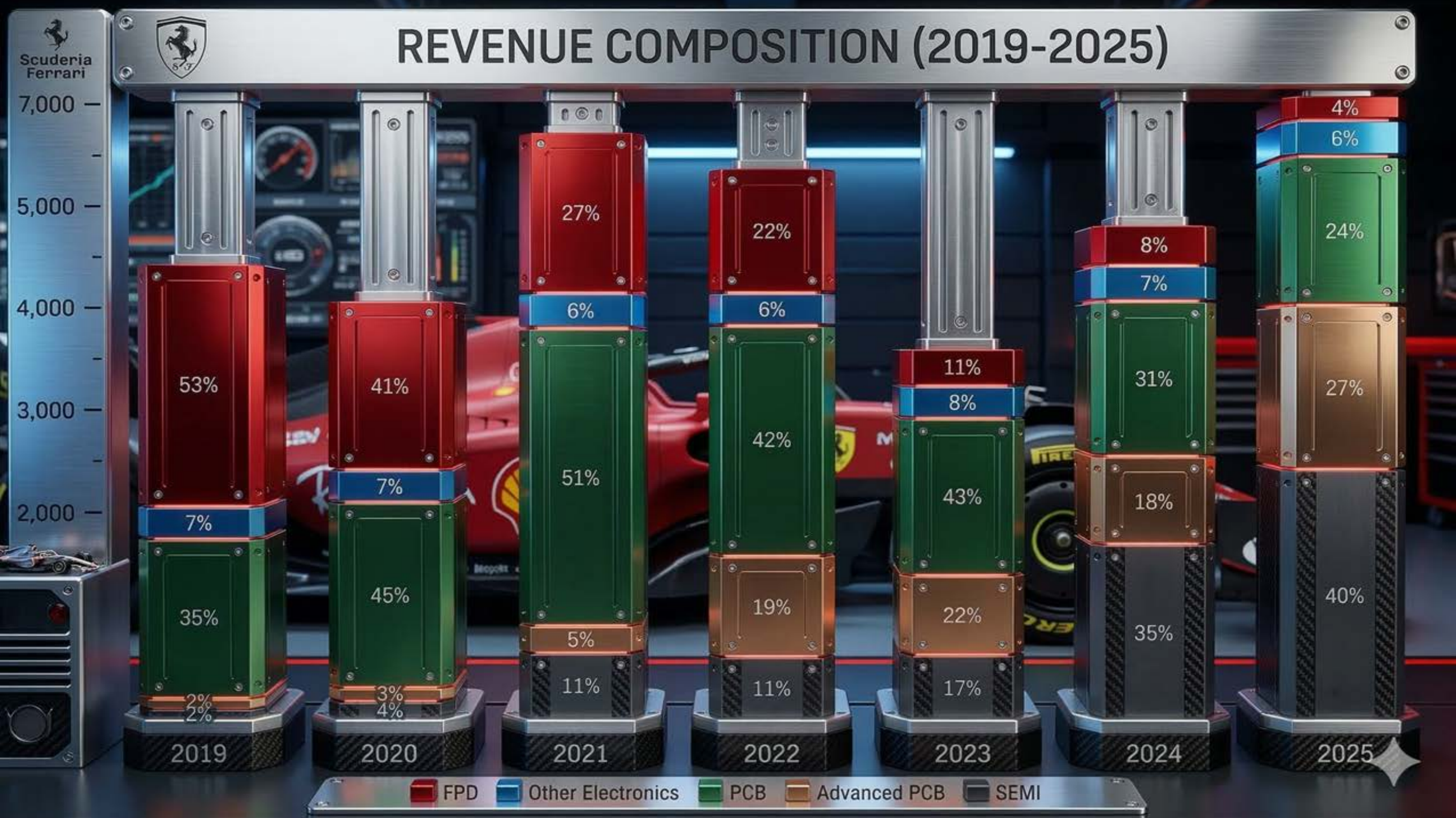
Professional Collaborative Team on the AI Track

Continuous Recognition from Champion Team

2023:
Excellent Production Support
(卓越量產支援)

2024:
Outstanding Improvement
(傑出持續改善)

2025:
Excellent Production Support
(卓越量產支援)


Scuderia Ferrari
REVENUE COMPOSITION (2019-2025)
7,000
5,000
4,000
3,000
2,000
53%
7%
35%
2%
2%
41%
7%
45%
3%
4%
27%
6%
51%
5%
11%
22%
6%
42%
19%
11%
11%
8%
43%
22%
17%
8%
7%
31%
18%
35%
4%
6%
24%
27%
40%
2019
2020
2021
2022
2023
2024
2025
FPD
Other Electronics
PCB
Advanced PCB
SEMI

2025 Financial Highlights: Structural Transformation & Record Highs

2025 Revenue

NT$ 6.1 Billion

Record High

2025 EPS

NT$ 5.50

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R&D Resource Allocation & Tech Upgrade

Next-Gen Processes & Equipment Upgrade for Advanced Packaging Supply Chain

Investments during the tech upgrade phase will support growth momentum for the next 3-5 years.

2026 Opening: Record-High Cumulative Revenue

Customers' CAPEX continues to flow in, providing sustainable momentum for future growth.

Dynamically aligning with customers' delivery schedules.

TSMC, intel, GF
FOUNDRY ACCESS TRACK
InFO
SoIC
EMIB
X-CUBE
WMCM
TSMC | intel | GF
OSAT
AI substrate & HDI
AI SUBSTRATE & HDI
ACCESS TRACK
ABF
HDI
SAP
mSAP
OSAT
ACCESS TRACK
Adv. PLP
SoIC
InFO
FlipChip
FoPLP
FoCoS
CoWoS
CoWoS
CoWoP
CoWoP
CoWoS
Advanced Packaging
GRAND CIRCUIT
GRAND CIRCUIT
mSAP

C SUN & G2C+

'DRIVING GROWTH THROUGH STRATEGIC EVOLUTION'

GERMANY + fab

JAPAN + fab

USA ARIZONA + fab

GLOBALIZATION SHIFT

C SUN CAPEX AWARD

PIT STOP & COMMON STARTING GRID

Energy Injections

Technical checkups

Parts

THE PIT CREW: C SUN & G2C+

AI

ENGINE I: FOUNDRY 2.0 GLOBALIZATION
THE GLOBALIZED FOUNDRY TRACK

FOPLP

HBM

FOPLP & HBM INTEGRATION

ENGINE II: AI-DRIVEN PROCESS DIVERSIFICATION.
THE AI PROCESS TRACK

AI complexity drives diversification

FINISH LINE

ENGINE III: ADVANCED PCB & REGIONAL SHIFT.
THE IC SUBSTRATE PCB TRACK

ASP Upgrade → Profitability

SOUTH EAST ASIA REGIONAL SHIFT

Technology Roadmap: Full Spectrum Coverage

Not only capitalizing on current advanced packaging dividends, but already positioned for future new process demands over the next 3 years.

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Building the Nest: R&D Center & Global Expansion

NT$ 1.82 Billion

Establishing an R&D center to enable the development of diversified next-generation equipment.

USA

Japan

台中水湳研發中心
(Taichung Shuinan R&D Center)
The Innovation Hub

精科二廠
(Jingke Plant 2)
Capacity Expansion

NT$ 1.48 Billion

Heavy investment in plants and facilities to ensure capacity security for the next 5 years.

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F1 ADVANCED PACKAGING GRAND PRIX
Foundry Main Track
CoWoS / SoIC / WMCM
TSMC
tsmc
OSAT Track
PLP / oS / Bumping / CoW / EMIB
ASE
PTI
AI Substrate & HDI Track
IC Substrate / HDI
Unimicron
Zhen Ding